CLAIMS

[1] A resin composition comprising:

(A) copper particles having an average particle diameter of 0.1 to 20 μm;

(B) a phosphoric acid-modified epoxy resin obtained by reacting a phosphoric acid (b1) with an epoxy compound (b2); ~~and~~

(C) a curing agent; and

(D) at least one resin selected from the group consisting of a xylene resin and a phenol resin,

~~w~~wherein

~~a~~ a content of the component (B), ~~and~~ a content of the component (C) and a content of the component (D), based on 100 parts by mass of the total amount of components (A) to (C), are 0.1 to 30 parts by mass, ~~and~~ 0.1 to 5 parts by mass and 1 to 30 parts by mass, respectively, and

wherein the copper particles comprise both of granular copper particles and flake-like copper particles.

~~[2] The resin composition according to claim 1, further comprising (D) at least one resin selected from the group consisting of a xylene resin, a phenol resin, and an epoxy resin (excluding the component (B)), wherein~~

~~a content of the component (D) based on 100 parts by mass of the total amount of the components (A) to (C) is 1 to 30 parts by mass.~~

[2~~3~~] A method for forming a cured product, comprising:

an application step of applying the resin composition according to claim 1 ~~or 2~~ on a substrate; and

a curing step of curing the resin composition by heating the substrate on which the resin composition has been applied.

[3~~4~~] The method for forming a cured product according to

claim 2~~3~~, wherein the substrate on which the resin composition has been applied is heated at 50 to 250°C for 1 to 200 minutes.

[4~~5~~] A cured product obtained by curing the resin composition according to claim 1~~ or 2~~.